

74LCX32

Low Voltage Quad 2-Input OR Gate with 5V Tolerant Inputs

General Description

The LCX32 contains four 2-input OR gates. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems.

The 74LCX32 is fabricated with advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs
- 2.3V–3.6V V_{CC} specifications provided
- 5.5 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μA I_{CC} max
- Power down high impedance inputs and outputs
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
 - Human body model > 2000V
 - Machine model > 150V
- Leadless Pb-Free DQFN package

Ordering Code:

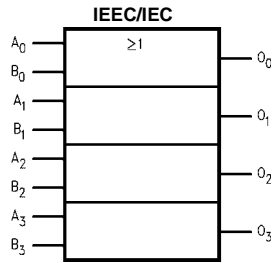
| Order Number | Package Number | Package Description |
|----------------------------|----------------|---|
| 74LCX32M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74LCX32MX_NL (Note 2) | M14A | Pb-Free 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74LCX32SJ | M14D | Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LCX32BQX (Note 1) | MLP014A | Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm |
| 74LCX32MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| 74LCX32MTCX_NL (Note 2) | MTC14 | Pb-Free 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.
Pb-Free package per JEDEC J-STD-020B.

Note 1: DQFN package available in Tape and Reel only.

Note 2: "_NL" indicates Pb-Free package (per JEDEC J-STD-020B). Device available in Tape and Reel only.

Logic Symbol

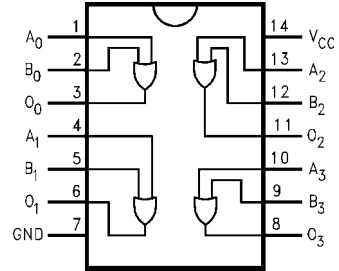


Pin Descriptions

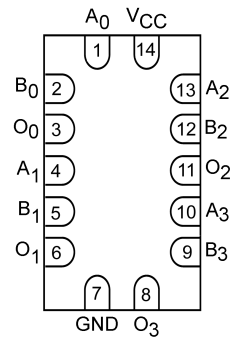
| Pin Names | Description |
|------------|-------------|
| A_n, B_n | Inputs |
| O_n | Outputs |

Connection Diagrams

Pin Assignments for SOIC, SOP, and TSSOP



Pad Assignment for DQFN



(Top View)

| Absolute Maximum Ratings ^(Note 3) | | | | | | |
|--|--|--|--------------------------------------|---------------------------------|------|-------|
| Symbol | Parameter | Value | Conditions | Units | | |
| V _{CC} | Supply Voltage | -0.5 to +7.0 | | V | | |
| V _I | DC Input Voltage | -0.5 to +7.0 | | V | | |
| V _O | DC Output Voltage | -0.5 to V _{CC} + 0.5 | Output in HIGH or LOW State (Note 4) | V | | |
| I _{IK} | DC Input Diode Current | -50 | V _I < GND | mA | | |
| I _{OK} | DC Output Diode Current | -50 | V _O < GND | mA | | |
| | | +50 | V _O > V _{CC} | | | |
| I _O | DC Output Source/Sink Current | ±50 | | mA | | |
| I _{CC} | DC Supply Current per Supply Pin | ±100 | | mA | | |
| I _{GND} | DC Ground Current per Ground Pin | ±100 | | mA | | |
| T _{STG} | Storage Temperature | -65 to +150 | | °C | | |
| Recommended Operating Conditions (Note 5) | | | | | | |
| Symbol | Parameter | Min | Max | Units | | |
| V _{CC} | Supply Voltage | Operating | 2.0 | 3.6 | V | |
| | | Data Retention | 1.5 | 3.6 | | |
| V _I | Input Voltage | 0 | 5.5 | V | | |
| V _O | Output Voltage | 0 | V _{CC} | V | | |
| I _{OH} /I _{OL} | Output Current | V _{CC} = 3.0V - 3.6V | | ±24 | mA | |
| | | V _{CC} = 2.7V - 3.0V | | ±12 | | |
| | | V _{CC} = 2.3V - 2.7V | | ±8 | | |
| T _A | Free-Air Operating Temperature | -40 | 85 | °C | | |
| Δt/ΔV | Input Edge Rate, V _{IN} = 0.8V-2.0V, V _{CC} = 3.0V | 0 | 10 | ns/V | | |
| <p>Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.</p> <p>Note 4: I_O Absolute Maximum Rating must be observed.</p> <p>Note 5: Unused inputs must be held HIGH or LOW. They may not float.</p> | | | | | | |
| DC Electrical Characteristics | | | | | | |
| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = -40°C to +85°C | | Units |
| | | | | Min | Max | |
| V _{IH} | HIGH Level Input Voltage | | 2.3 - 2.7 | 1.7 | | V |
| | | | 2.7 - 3.6 | 2.0 | | |
| V _{IL} | LOW Level Input Voltage | | 2.3 - 2.7 | | 0.7 | V |
| | | | 2.7 - 3.6 | | 0.8 | |
| V _{OH} | HIGH Level Output Voltage | I _{OH} = -100 μA | 2.3 - 3.6 | V _{CC} - 0.2 | | V |
| | | I _{OH} = -8 mA | 2.3 | 1.8 | | |
| | | I _{OH} = -12 mA | 2.7 | 2.2 | | |
| | | I _{OH} = -18 mA | 3.0 | 2.4 | | |
| | | I _{OH} = -24 mA | 3.0 | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | I _{OL} = 100 μA | 2.3 - 3.6 | | 0.2 | V |
| | | I _{OL} = 8 mA | 2.3 | | 0.6 | |
| | | I _{OL} = 12 mA | 2.7 | | 0.4 | |
| | | I _{OL} = 16 mA | 3.0 | | 0.4 | |
| | | I _{OL} = 24 mA | 3.0 | | 0.55 | |
| I _I | Input Leakage Current | 0 ≤ V _I ≤ 5.5V | 2.3 - 3.6 | | ±5.0 | μA |
| I _{OFF} | Power-Off Leakage Current | V _I or V _O = 5.5V | 0 | | 10 | μA |
| I _{CC} | Quiescent Supply Current | V _I = V _{CC} or GND | 2.3 - 3.6 | | 10 | μA |
| | | 3.6V ≤ V _I ≤ 5.5V | 2.3 - 3.6 | | ±10 | |
| ΔI _{CC} | Increase in I _{CC} per Input | V _{IH} = V _{CC} - 0.6V | 2.3 - 3.6 | | 500 | μA |

AC Electrical Characteristics

| Symbol | Parameter | $T_A = -40^{\circ}\text{C to }+85^{\circ}\text{C}, R_L = 500\Omega$ | | | | | | Units |
|------------|-------------------|---|-----|----------------------|-----|--------------------------|-----|-------|
| | | $V_{CC} = 3.3V \pm 0.3V$ | | $V_{CC} = 2.7V$ | | $V_{CC} = 2.5V \pm 0.2V$ | | |
| | | $C_L = 50\text{ pF}$ | | $C_L = 50\text{ pF}$ | | $C_L = 30\text{ pF}$ | | |
| | | Min | Max | Min | Max | Min | Max | |
| t_{PHL} | Propagation Delay | 1.5 | 5.5 | 1.5 | 6.2 | 1.5 | 6.6 | ns |
| t_{PLH} | | 1.5 | 5.5 | 1.5 | 6.2 | 1.5 | 6.6 | |
| t_{OSHL} | Output to Output | | 1.0 | | | | | ns |
| t_{OSLH} | Skew (Note 6) | | 1.0 | | | | | |

Note 6: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

| Symbol | Parameter | Conditions | V_{CC} (V) | $T_A = 25^{\circ}\text{C}$ | Units |
|-----------|--------------------------------------|--|-----------------|----------------------------|-------|
| | | | | Typical | |
| V_{OLP} | Quiet Output Dynamic Peak V_{OL} | $C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$ $C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$ | 3.3 2.5 | 0.8 0.6 | V |
| V_{OLV} | Quiet Output Dynamic Valley V_{OL} | $C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$ $C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$ | 3.3 2.5 | -0.8 -0.6 | V |

Capacitance

| Symbol | Parameter | Conditions | Typical | Units |
|-----------|-------------------------------|---|---------|-------|
| C_{IN} | Input Capacitance | $V_{CC} = \text{Open}, V_I = 0V \text{ or } V_{CC}$ | 7 | pF |
| C_{OUT} | Output Capacitance | $V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}$ | 8 | pF |
| C_{PD} | Power Dissipation Capacitance | $V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}, f = 10\text{ MHz}$ | 25 | pF |

AC Loading and Waveforms Generic for LCX Family

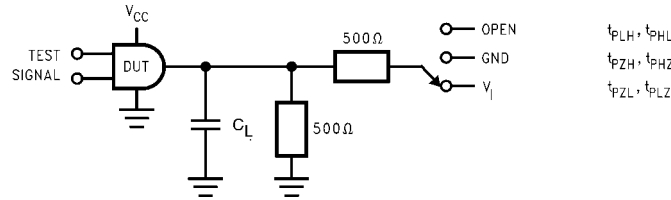


FIGURE 1. AC Test Circuit
(C_L includes probe and jig capacitance)

| Test | Switch |
|--------------------|---|
| t_{PLH}, t_{PHL} | Open |
| t_{PZL}, t_{PLZ} | 6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$ |
| t_{PZH}, t_{PHZ} | GND |

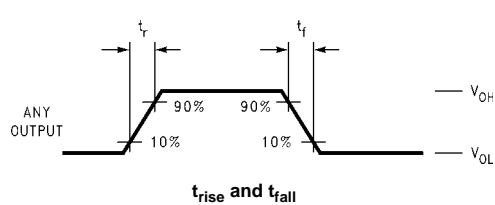
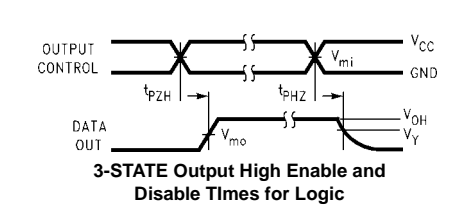
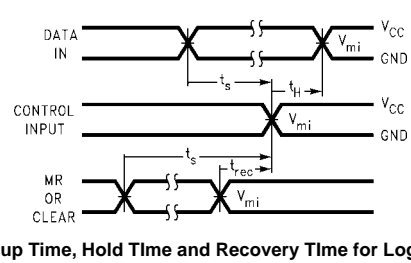
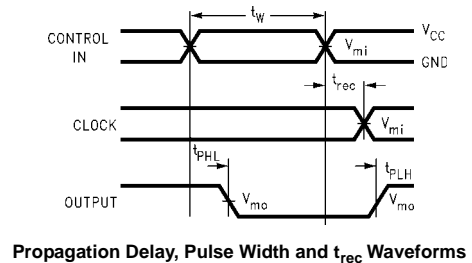
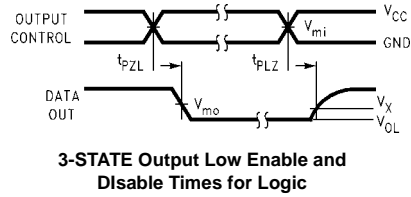
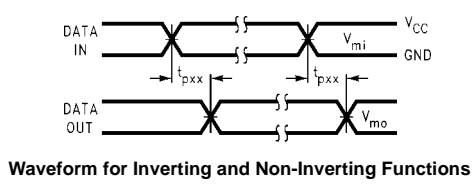
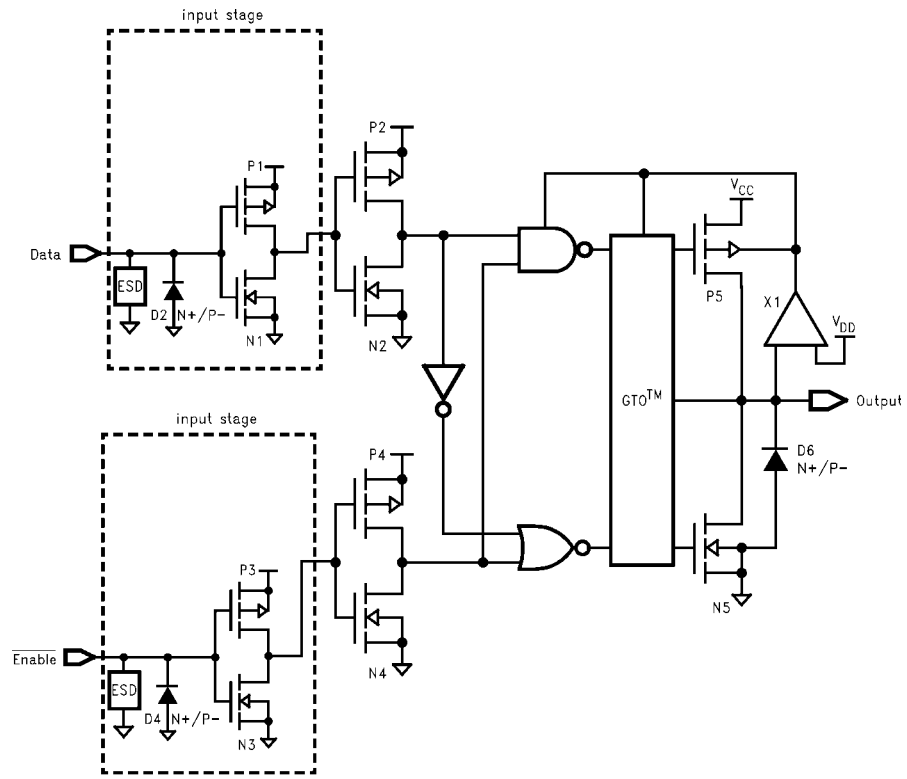


FIGURE 2. Waveforms
(Input Pulse Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | $3.3V \pm 0.3V$ | $2.7V$ | $2.5V \pm 0.2V$ |
| V_{mi} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_{mo} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

Schematic Diagram Generic for LCX Family



| Tape and Reel Specification | | | | |
|-----------------------------|--------------------|-----------------|---------------|-------------------|
| Tape Format for DQFN | | | | |
| Package Designator | Tape Section | Number Cavities | Cavity Status | Cover Tape Status |
| BQX | Leader (Start End) | 125 (typ) | Empty | Sealed |
| | Carrier | 2500/3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (typ) | Empty | Sealed |

TAPE DIMENSIONS inches (millimeters)

| PKG. SIZE | DIM.Ao | DIM.Bo | DIM.Ko |
|-----------|-----------|-----------|-----------|
| 3.5 X 4.5 | 3.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 3.0 X 3.0 | 3.3 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 4.5 | 2.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.5 | 2.8 ± 0.1 | 3.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.0 | 2.8 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 2.5 | 2.8 ± 0.1 | 2.8 ± 0.1 | 0.9 ± 0.1 |

DIMENSIONS ARE IN MILLIMETERS

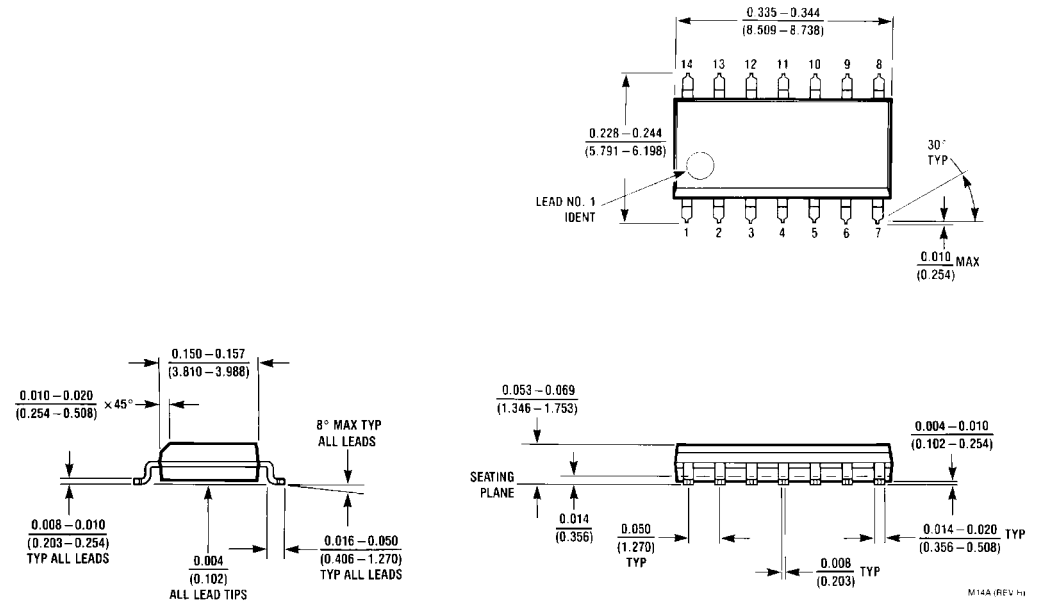
NOTES: unless otherwise specified

- Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
- Smallest allowable bending radius.
- Thru hole inside cavity is centered within cavity.
- Tolerance is ±0.002[0.05] for these dimensions on all 12mm tapes.
- Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
- Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
- Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
- Controlling dimension is millimeter. Dimension in inches rounded.

REEL DIMENSIONS inches (millimeters)

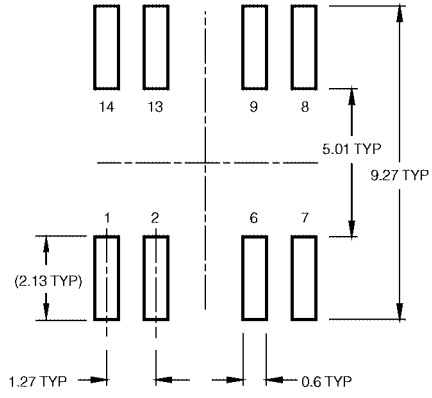
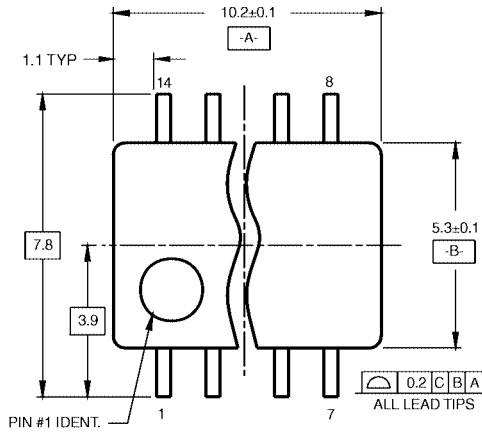
| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|---------------|-----------------|------------------|------------------|----------------|-----------------|-----------------|
| 12 mm | 13.0 (330) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 7.008 (178) | 0.488 (12.4) | 0.724 (18.4) |

Physical Dimensions inches (millimeters) unless otherwise noted

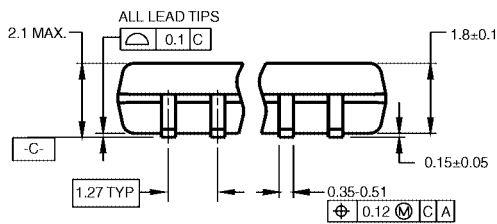


**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M14A**

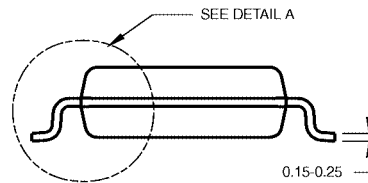
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION

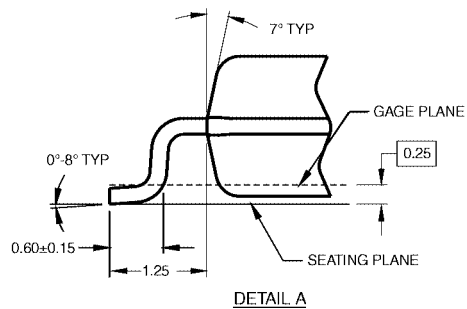


DIMENSIONS ARE IN MILLIMETERS



- NOTES:
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

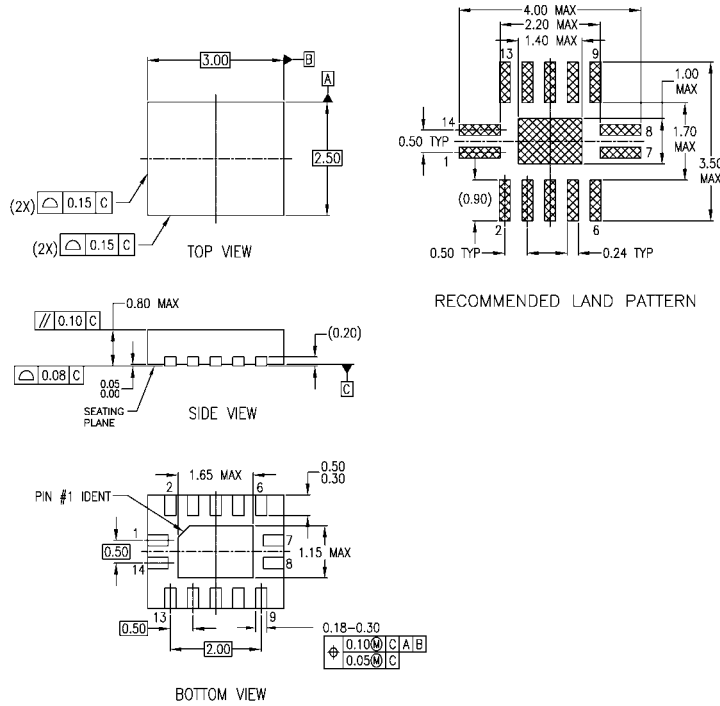
M14DRevB1



DETAIL A

Pb-Free 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



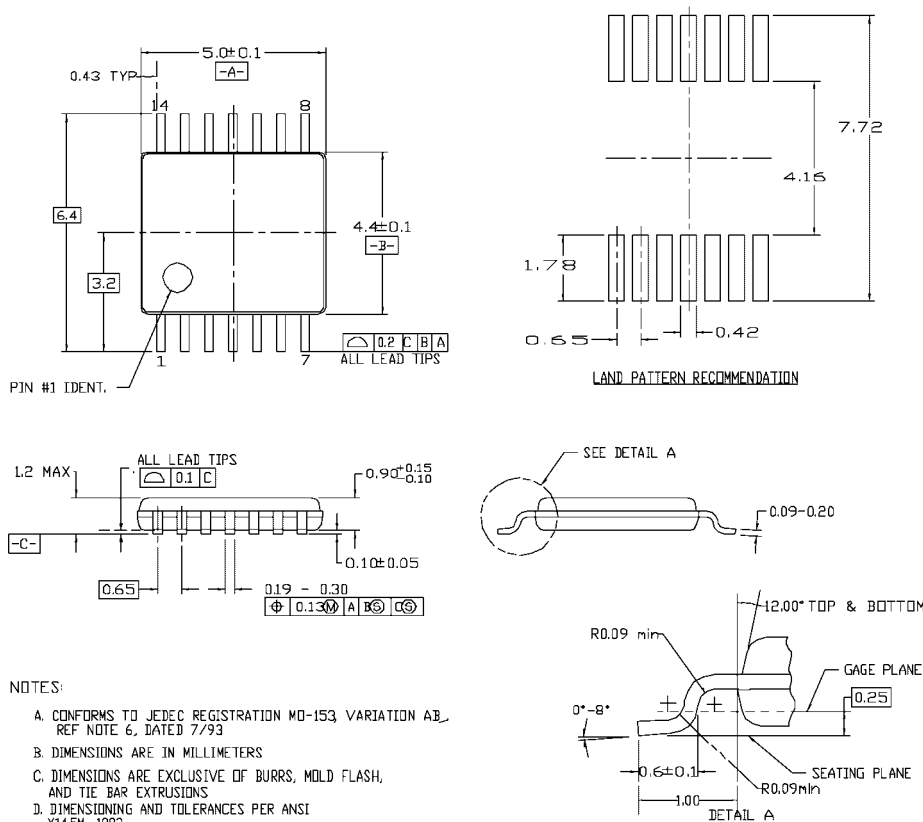
NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP014ArevA

Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm Package Number MLP014A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



- NOTES:
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATED 7/93
 - B. DIMENSIONS ARE IN MILLIMETERS
 - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

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